2-2308107-0 ACTIVE

DDR4 DIMM

TE Internal #: 2-2308107-0

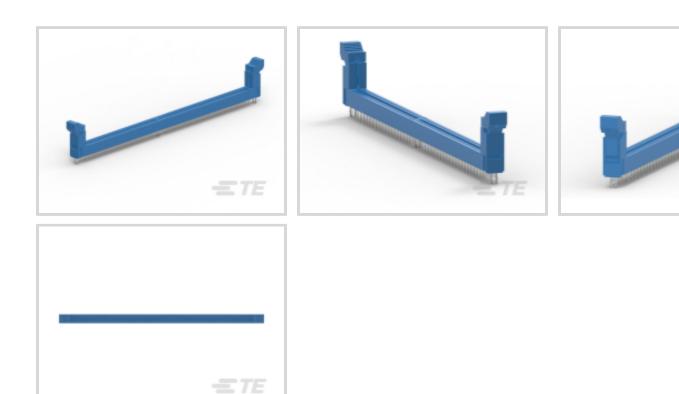
Double Data Rate (DDR) 4, Board-to-Bus Bar, 288 Position, Through Hole - Solder, Vertical Module Orientation, DDR4 DIMM, DIMM

Sockets

View on TE.com >



Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: Double Data Rate (DDR) 4

Connector System: Board-to-Bus Bar

Number of Positions: 288

Termination Method to PCB: Through Hole - Solder

Module Orientation: Vertical

All DDR4 DIMM SOCKETS (25)

Features

Product Type Features

PCB Retention Feature Material

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Bus Bar
Configuration Features	
Number of Keys	1
Number of Rows	2
Number of Positions	288
Module Orientation	Vertical
Electrical Characteristics	
DRAM Voltage	1.2 V
Body Features	

Stainless Steel



Ejector Material Color	Blue
Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic
Ejector Material	High Temperature Thermoplastic
Latch Color	Blue
Module Key Type	Offset Right
Connector Profile	Standard
Ejector Type	Standard
Contact Features	
Memory Socket Type	Memory Card
Socket Style	DIMM
Contact Mating Area Plating Material Thickness	.38 μm[15 μin]
Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A
Termination Features	
Insertion Style	Direct Insert
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Offset Right
Mating Alignment	Without
PCB Mount Retention	With
PCB Mount Retention Type	Boardlock
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	High Temperature Thermoplastic
Housing Color	Blue
Centerline (Pitch)	.85 mm[.033 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Operation/Application Circuit Application	Signal



Industry Standards

UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JAN 2019 (197) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



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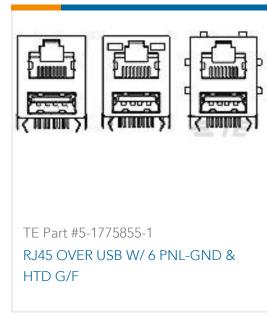
Also in the Series | DDR4 DIMM





Customers Also Bought





















Documents

Product Drawings DDR4 DIMM 288 PIN TH TYPE

English

CAD Files 3D PDF

3D

Double Data Rate (DDR) 4, Board-to-Bus Bar, 288 Position, Through Hole - Solder, Vertical Module Orientation, DDR4 DIMM, DIMM Sockets



Customer View Model

ENG_CVM_CVM_2-2308107-0_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2-2308107-0_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-2308107-0_1.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English